

**LISTING OF CLAIMS:**

This listing of claims will replace all prior versions and listings of claims in the application:

Claims 1-25. (Cancelled).

Claim 26. (New) A process for producing a plurality of components, comprising the steps of:

joining a first surface of a substrate to a first surface of a carrier with a bonding force;

machining the plurality of components out of the substrate, with the plurality of components being held together by the carrier at least immediately after they have been machined out;

releasing the bonding force between the carrier and the plurality of substrates; and

detaching the plurality of components from the carrier in order to separate the plurality of components.

Claim 27. (New) The process as claimed in claim 26, wherein the plurality of components are separated from one another laterally during the machining step.

Claim 28. (New) The process as claimed in claim 26, wherein the substrate comprises glass or a vitreous material.

Claim 29. (New) The process as claimed in claim 26, wherein the carrier comprises a carrier film.

Claim 30. (New) The process as claimed in claim 26, wherein the step of machining comprises removing material from a second surface of the substrate, the second surface being on the opposite side of the substrate from the first surface, the material removed being at least as far as the first surface of the substrate.

Claim 31. (New) The process as claimed in claim 30, the step of machining further comprises removing a portion of material from the first surface of the carrier.

Claim 32. (New) The process as claimed in claim 26, wherein the step of machining comprises removing portions of the substrate and the carrier in succession until a position between the first surface and a second surface of the carrier material is reached, the second surface being on the opposite side of the substrate from the first surface.

Claim 33. (New) The process as claimed in claim 26, wherein the step of machining comprises machining a multiplicity of laterally adjacent components out of the substrate in one working step.

Claim 34. (New) The process as claimed in claim 26, wherein the step of machining comprises vibratory lapping.

Claim 35. (New) The process as claimed in claim 34, wherein the vibratory lapping step comprises using a plurality of hollow lapping punches.

Claim 36. (New) The process as claimed in claim 35, wherein the plurality of hollow lapping punches have a cross section in the form of a continuous ring.

Claim 37. (New) The process as claimed in claim 26, wherein the step of machining comprises blasting with a blasting material.

Claim 38. (New) The process as claimed in claim 26, wherein the substrate has a second surface opposite the first surface, the second surface being a structured surface.

Claim 39. (New) The process as claimed in claim 26, wherein the detaching step comprises using a vacuum to separate the plurality of components from the carrier.

Claim 40. (New) The process as claimed in claim 26, further comprising applying a solder agent to at least a portion of a second surface of the substrate, the second surface of the substrate being on the opposite side of the substrate from the first surface.

Claim 41. (New) The process as claimed in claim 40, wherein the applying step comprises printing the solder agent on the portion of the second surface of the substrate in structured form as a solder-agent layer.

Claim 42. (New) The process as claimed in claim 40, further comprising applying a protective layer to the second surface of the substrate and/or to the solder-agent layer.

Claim 43. (New) The process as claimed in claim 42, further comprising removing the protective layer after the machining step and before the detaching step.

Claim 44. (New) A process for producing a plurality of components, comprising the steps of:

joining a carrier to a first surface of a substrate with a bonding force;

applying a solder-agent layer to a second surface of the substrate, the second surface being on the opposite side of the substrate from the first surface;

applying a protective layer to the second surface and to the solder-agent layer;

machining the plurality of components out of the substrate by removing material all the way through the protective layer and the substrate and by removing material only part way into the carrier;

removing the protective layer;

releasing the bonding force; and

detaching the plurality of components from the carrier.

Claim 45. (New) An intermediate product in the form of a layer composite, comprising:

a substrate divided into a multiplicity of laterally separated components; and a common sheet-like carrier having a first surface of each of the multiplicity of laterally separated components being releasably secured laterally adjacent to one another on the common sheet-like carrier.

Claim 46. (New) The intermediate product as claimed in claim 45, further comprising a solder-agent layer on a second surface of the substrate, the solder-agent layer being divided into a multiplicity of laterally separate portions, and each of the multiplicity of laterally separate portions being assigned to a specific one of the multiplicity of laterally separated components.

Claim 47. (New) The intermediate product as claimed in claim 46, wherein the solder-agent layer has a structured form.

Claim 48. (New) The intermediate product as claimed in claim 46, further comprising a protective layer on the second surface of the substrate and the solder-agent layer.

Claim 49. (New) The intermediate product as claimed in claim 45, further comprising a protective layer on a second surface of the substrate.

Claim 50. (New) The intermediate product as claimed in claim 49, wherein the protective layer is divided into a multiplicity of separate portions, and each of the multiplicity of laterally separate portions being assigned to a specific one of the multiplicity of laterally separated components.